

International Rectifier

HEXFET® POWER MOSFET

Provisional Data Sheet No. PD-9.423B

JANTX2N6782
JANTXV2N6782
[REF:MIL-PRF-19500/556]
[GENERIC:IRFF110]
N-CHANNEL

100 Volt, 0.60Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry achieves very low on-state resistance combined with high transconductance.

HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, and high energy pulse circuits, and virtually any application where high reliability is required.

Product Summary

Part Number	BVDSS	RDS(on)	ID
JANTX2N6782	100V	0.60Ω	3.5A
JANTXV2N6782			

Features:

- Avalanche Energy Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed

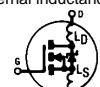
Absolute Maximum Ratings

	Parameter	JANTX2N6782, JANTXV2N6782	Units
ID @ VGS = 10V, TC = 25°C	Continuous Drain Current	3.5	A
ID @ VGS = 10V, TC = 100°C	Continuous Drain Current	2.25	
IMD	Pulsed Drain Current ①	14	
PD @ TC = 25°C	Max. Power Dissipation	15	W
	Linear Derating Factor	0.12	W/K ⑤
VGS	Gate-to-Source Voltage	±20	V
dv/dt	Peak Diode Recovery dv/dt ③	5.5	V/ns
TJ TSTG	Operating Junction Storage Temperature Range	-55 to 150	°C
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10.5 seconds)	
	Weight	0.98 (typical)	

JANTX2N6782, JANTXV2N6782 Device

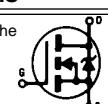
Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (Unless Otherwise Specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BVDSS	Drain-to-Source Breakdown Voltage	100	—	—	V	$V_{GS} = 0\text{V}, I_D = 1.0\text{ mA}$
$\Delta BVDSS/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	—	0.10	—	$\text{V}/^\circ\text{C}$	Reference to 25°C , $I_D = 1.0\text{ mA}$
RDS(on)	Static Drain-to-Source On-State Resistance	—	—	0.60	Ω	$V_{GS} = 10\text{V}, I_D = 2.25\text{A}$ ^④
		—	—	0.69		$V_{GS} = 10\text{V}, I_D = 3.5\text{A}$
VGS(th)	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
gfs	Forward Transconductance	0.8	—	—	S (mS)	$V_{DS} > 15\text{V}, I_{DS} = 2.25\text{A}$ ^④
IDSS	Zero Gate Voltage Drain Current	—	—	25	μA	$V_{DS} = 0.8 \times \text{Max Rating}, V_{GS} = 0\text{V}$
		—	—	250		$V_{DS} = 0.8 \times \text{Max Rating}$ $V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$
IGSS	Gate-to-Source Leakage Forward	—	—	100	nA	$V_{GS} = 20\text{V}$
IGSS	Gate-to-Source Leakage Reverse	—	—	-100		$V_{GS} = -20\text{V}$
Qg	Total Gate Charge	4.1	—	6.5	nC	$V_{GS} = 10\text{V}, I_D = 3.5\text{A}$
Qgs	Gate-to-Source Charge	0.4	—	1.6		$V_{DS} = \text{Max. Rating} \times 0.5$ see figures 6 and 13
Qgd	Gate-to-Drain ("Miller") Charge	1.4	—	3.5	ns	$V_{DD} = 50\text{V}, I_D = 3.5\text{A},$ $R_G = 7.5\Omega, V_{GS} = 10\text{V}$ see figure 10
td(on)	Turn-On Delay Time	—	—	15		
tr	Rise Time	—	—	25		
td(off)	Turn-Off Delay Time	—	—	25		
tf	Fall Time	—	—	20		
LD	Internal Drain Inductance	—	5.0	—	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die.
LS	Internal Source Inductance	—	15.0	—		Measured from the source lead, 6mm (0.25 in.) from package bonding pad.
Ciss	Input Capacitance	—	180	—	pF	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}$ $f = 1.0\text{ MHz}$ see figure 5
Coss	Output Capacitance	—	82	—		
Crss	Reverse Transfer Capacitance	—	15	—		



Source-Drain Diode Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
IS	Continuous Source Current (Body Diode)	—	—	3.5	A	Modified MOSFET symbol showing the integral reverse p-n junction rectifier.
ISM	Pulse Source Current (Body Diode) ^①	—	—	14		
VSD	Diode Forward Voltage	—	—	1.5	V	$T_j = 25^\circ\text{C}, I_S = 3.5\text{A}, V_{GS} = 0\text{V}$ ^④
t _{rr}	Reverse Recovery Time	—	—	180	ns	$T_j = 25^\circ\text{C}, I_F = 3.5\text{A}, dI/dt \leq 100\text{A}/\mu\text{s}$
QRR	Reverse Recovery Charge	—	—	2.0	μC	$V_{DD} \leq 50\text{V}$ ^④
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$.				



Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R _{thJC}	Junction-to-Case	—	—	8.3	K/W	Typical socket mount
	Junction-to-Ambient	—	—	175		

JANTX2N6782, JANTXV2N6782 Device

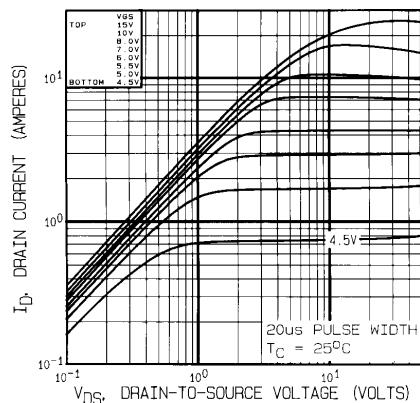


Fig. 1 — Typical Output Characteristics
 $T_C = 25^\circ\text{C}$

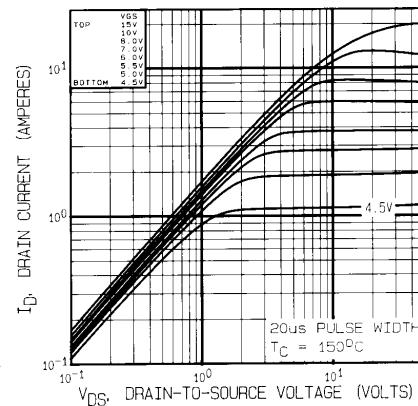


Fig. 2 — Typical Output Characteristics
 $T_C = 150^\circ\text{C}$

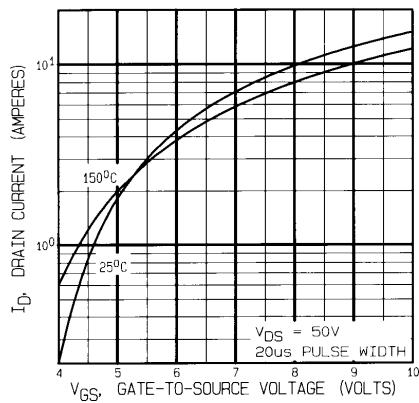


Fig. 3 — Typical Transfer Characteristics

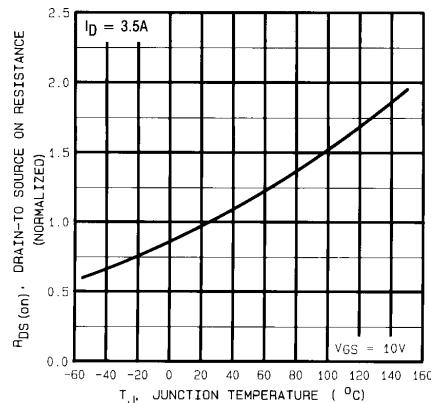


Fig. 4 — Normalized On-Resistance Vs. Temperature

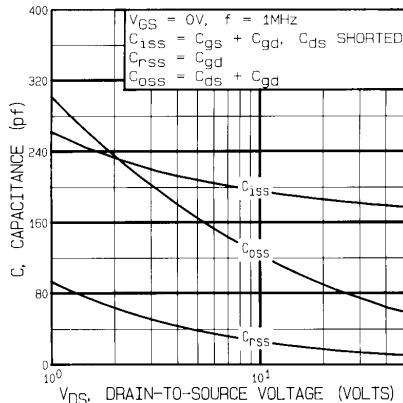


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

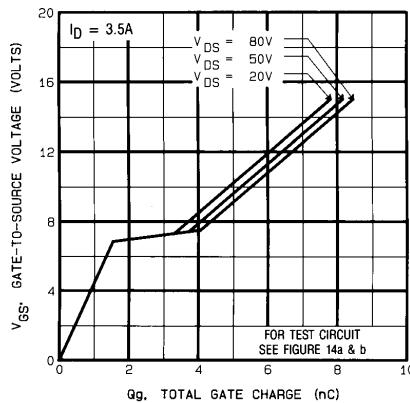


Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage

JANTX2N6782, JANTXV2N6782 Device

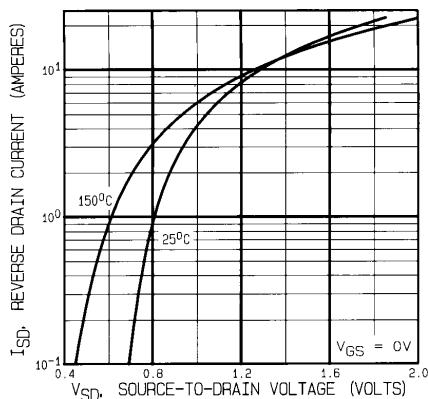


Fig. 7 — Typical Source-to-Drain Diode Forward Voltage

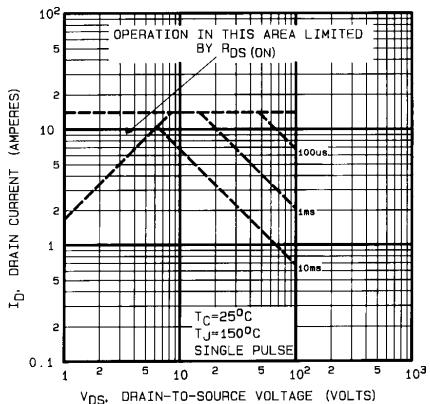


Fig. 8 — Maximum Safe Operating Area

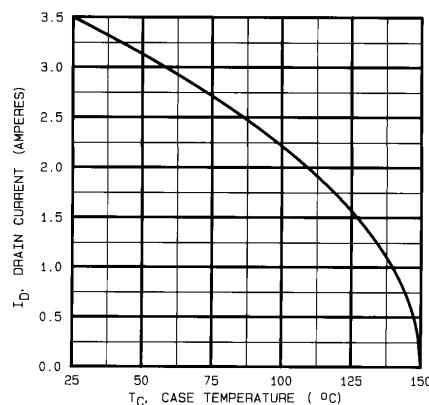


Fig. 9 — Maximum Drain Current Vs. Case Temperature

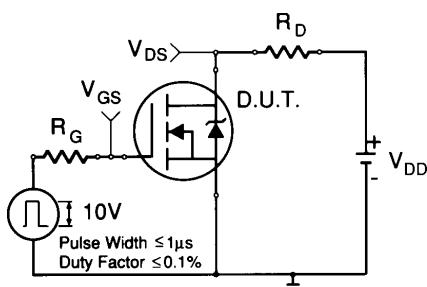


Fig. 10a — Switching Time Test Circuit

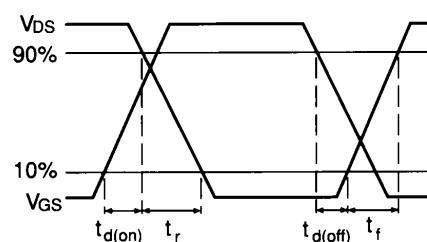


Fig. 10b — Switching Time Waveforms

JANTX2N6782, JANTXV2N6782 Device

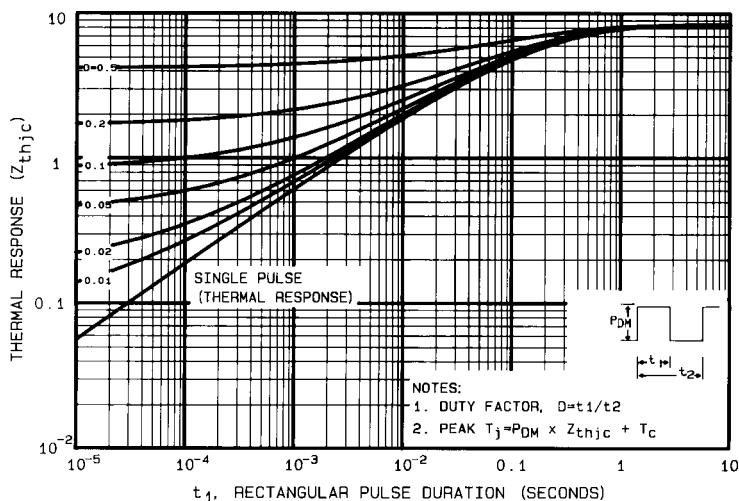


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

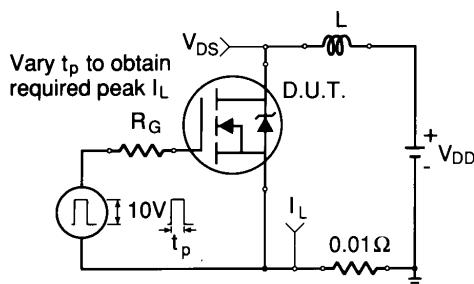


Fig. 12a — Unclamped Inductive Test Circuit

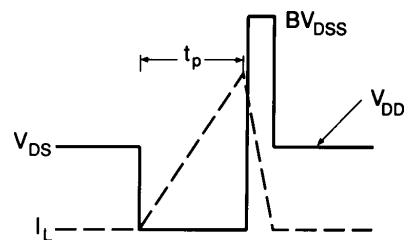


Fig. 12b — Unclamped Inductive Waveforms

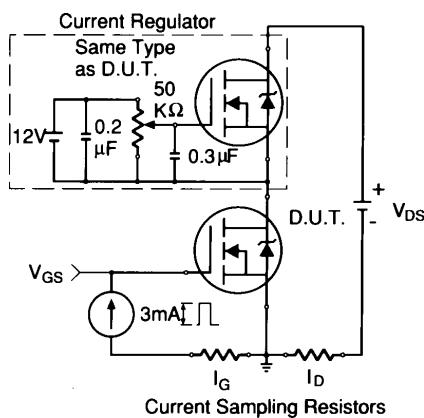


Fig. 13a — Gate Charge Test Circuit

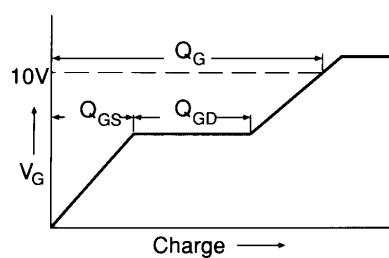
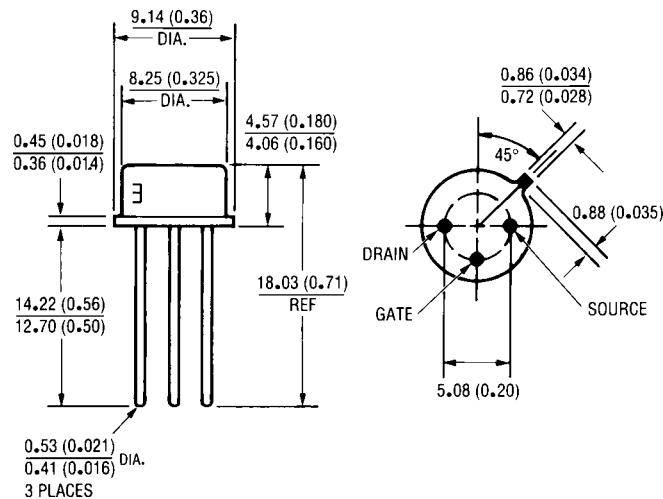
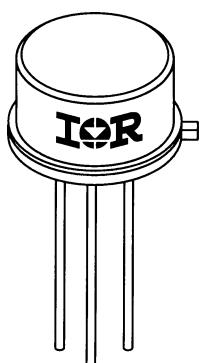


Fig. 13b — Basic Gate Charge Waveform

JANTX2N6782, JANTXV2N6782 Device

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
(see figure 11)
- ② @ V_{DD} = 25V, Starting T_J = 25°C,
EAS = [0.5 * L * (I_L²) * [BV_{DSS}/(BV_{DSS}-V_{DD})]]
Peak I_L = 3.5A, V_{GS} = 10V, 25 ≤ R_G ≤ 200Ω
- ③ ISD ≤ 3.5A, di/dt ≤ 75A/μs,
V_{DD} ≤ BV_{DSS}, T_J ≤ 150°C
- ④ Pulse width ≤ 300 μs; Duty Cycle ≤ 2%
- ⑤ K/W = °C/W
W/K = W/°C

Case Outline and Dimensions — TO-205AF (TO-39)



All dimensions are shown millimeters (inches)

International
IR Rectifier

WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, Tel: (310) 322 3331

EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44 1883 732020

IR CANADA: 7321 Victoria Park Ave., Suite 201, Markham, Ontario L3R 2Z8, Tel: (905) 475 1897

IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590

IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111

IR FAR EAST: K&H Bldg., 2F, 3-30-4 Nishi-Ikeburo 3-Chome, Toshima-Ki, Tokyo Japan 171 Tel: 81 3 3983 0086

IR SOUTHEAST ASIA: 315 Outram Road, #10-02 Tan Boon Liat Building, Singapore 0316 Tel: 65 221 8371

<http://www.irf.com/> Data and specifications subject to change without notice.

10/96